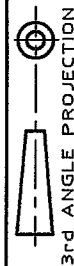


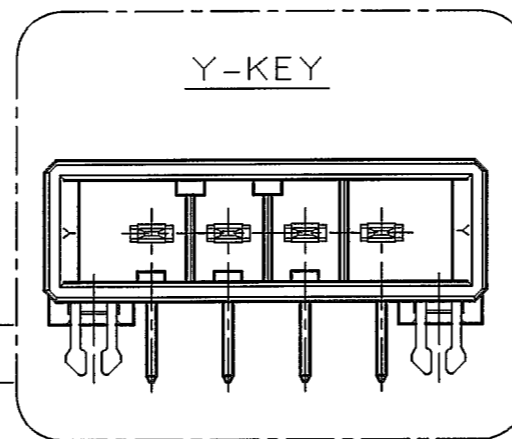
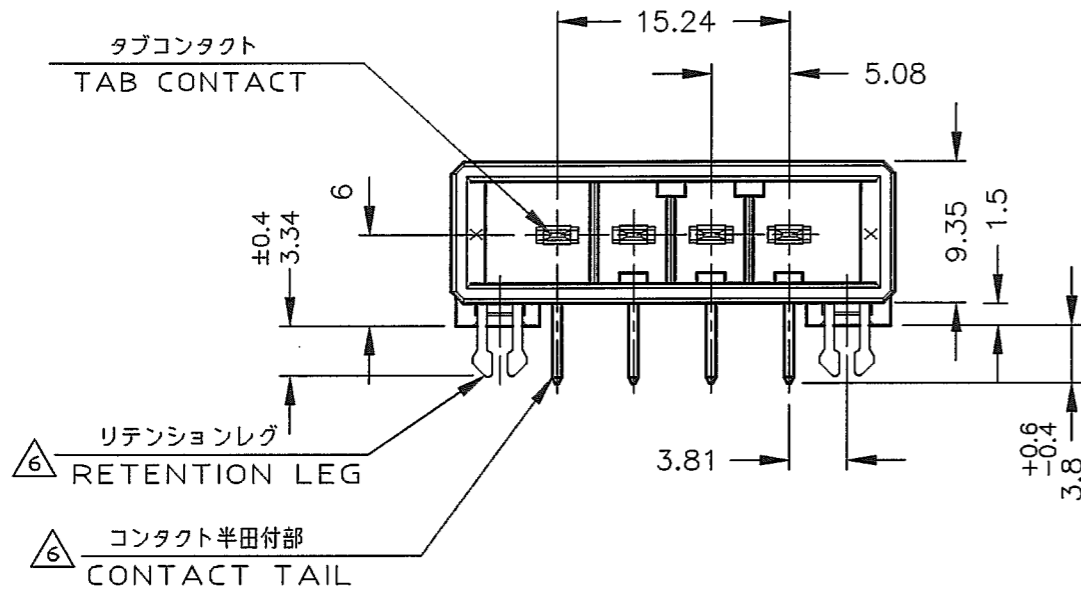
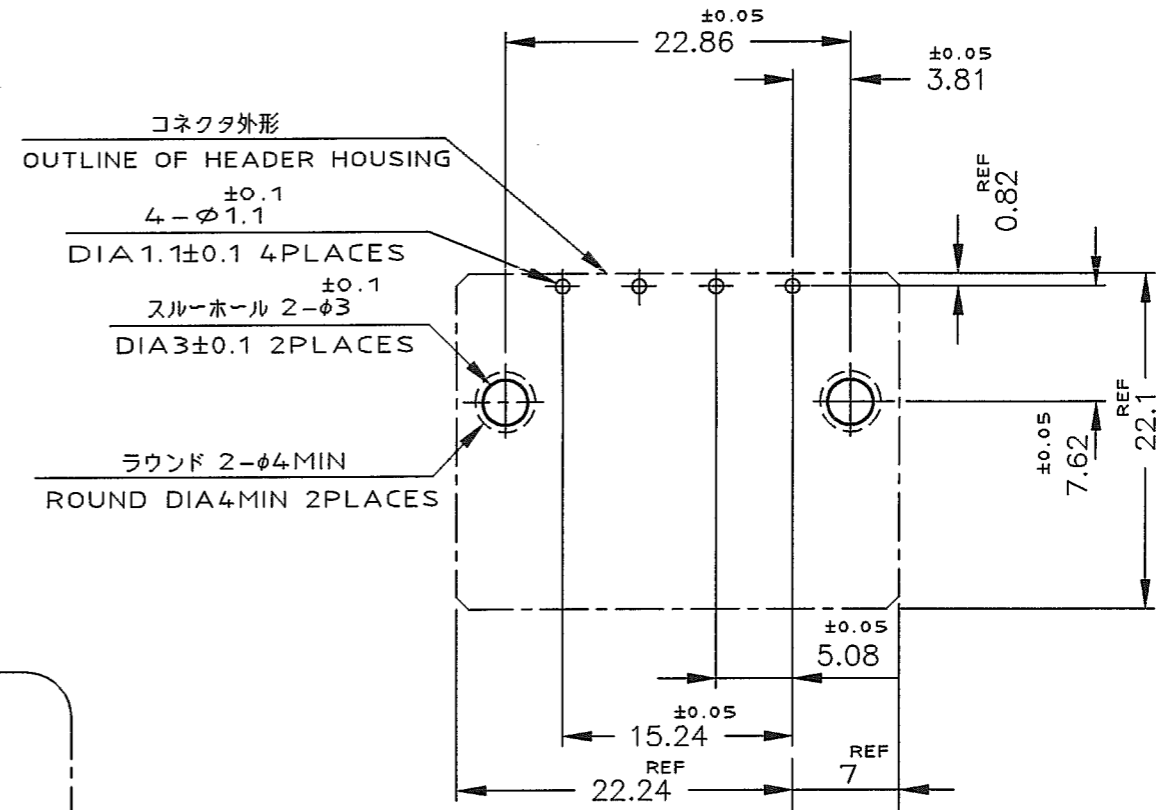
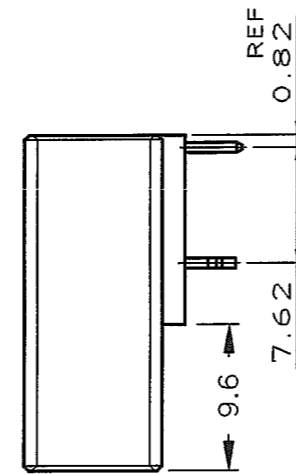
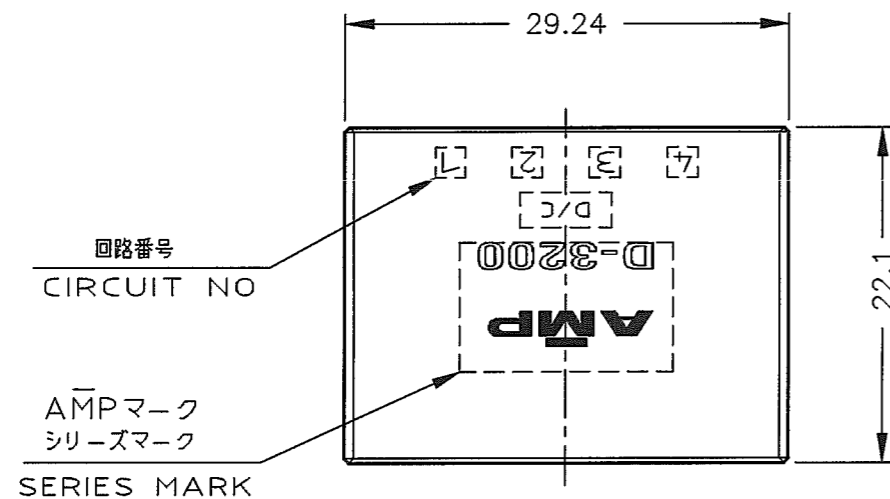
NUMBER 179277



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法
PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土に半田めっき
- めっき: リテンションレグとコンタクト半田付部: ニッケル下地の土にスズめっき

△6	△4	2-179277-5	Y
△6	△3	2-179277-3	Y
△6	△2	2-179277-2	Y
△6	△4	1-179277-5	X
△6	△3	1-179277-3	X
△6	△2	1-179277-2	X
(FINISH)	製品番号 (PART NO.)	KEY	

D1	REVISED PER ECO-11-005030	RK	HMR	23MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm ² (AWG -)		mmφ		4 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 10 DEC 93 N. Matsubara		DE. 10 DEC 93 N. Matsubara		SIZE A3	LOC J
CHK. 13 DEC 93 S. MANABE		APP. 13 DEC 93 S. MANABE		NUMBER C-179277	SCALE 2-1
				REV. D1	SHEET 1 OF 1

